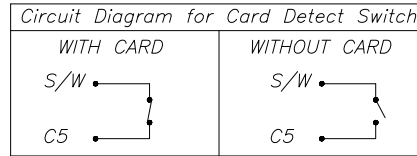


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



NOTES:

1. MATERIAL:

- 1.1 Housing: High Temperature Thermoplastic
UL94V-0; Color Black.
- 1.2 Terminal: Copper Alloy, T=0.12mm.
- 1.3 Shell: Stainless Steel, T=0.20mm.

2. FINISH:

- 2.1 Terminal: Plated Gold on the Contact Area and Solder Tails
- 2.2 Peg: Plated Gold on the Solder Tails.

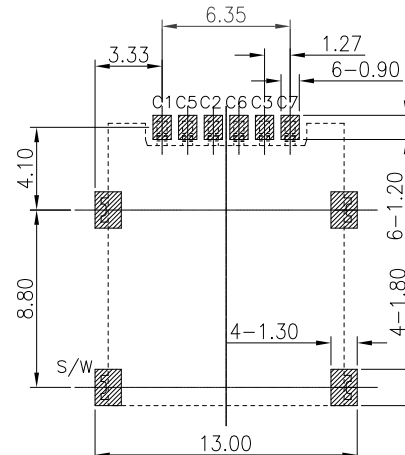
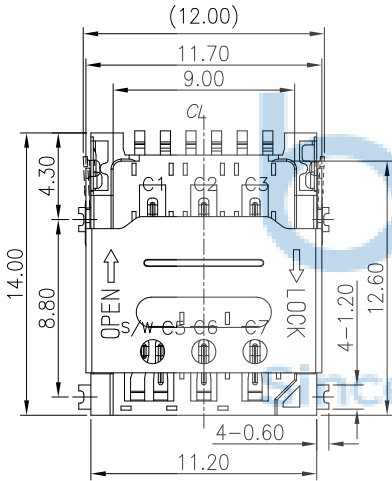
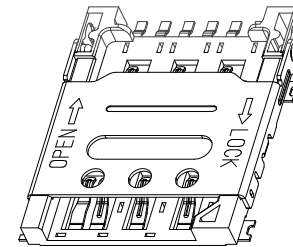
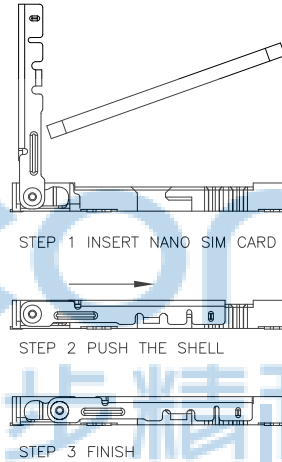
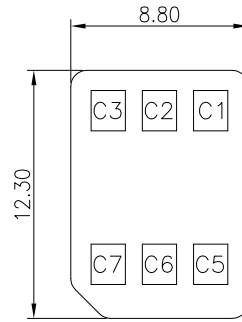
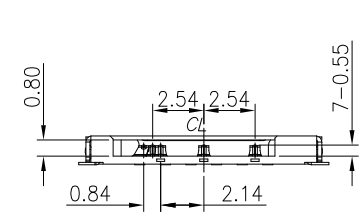
3. SPECIALITY:

- 3.1 Rated current: 0.5A
- 3.2 Rated voltage: 50V
- 3.3 Contact Resistance: 80mΩ MAX
- 3.4 Insulation Resistance: 100MΩMIN 100V DC
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Solder ability: 245±5° C, 5±0.5s.
- 3.7 Operating condition: Temperature: -30° C~+80° C
Humidity: 80% R.H MAX

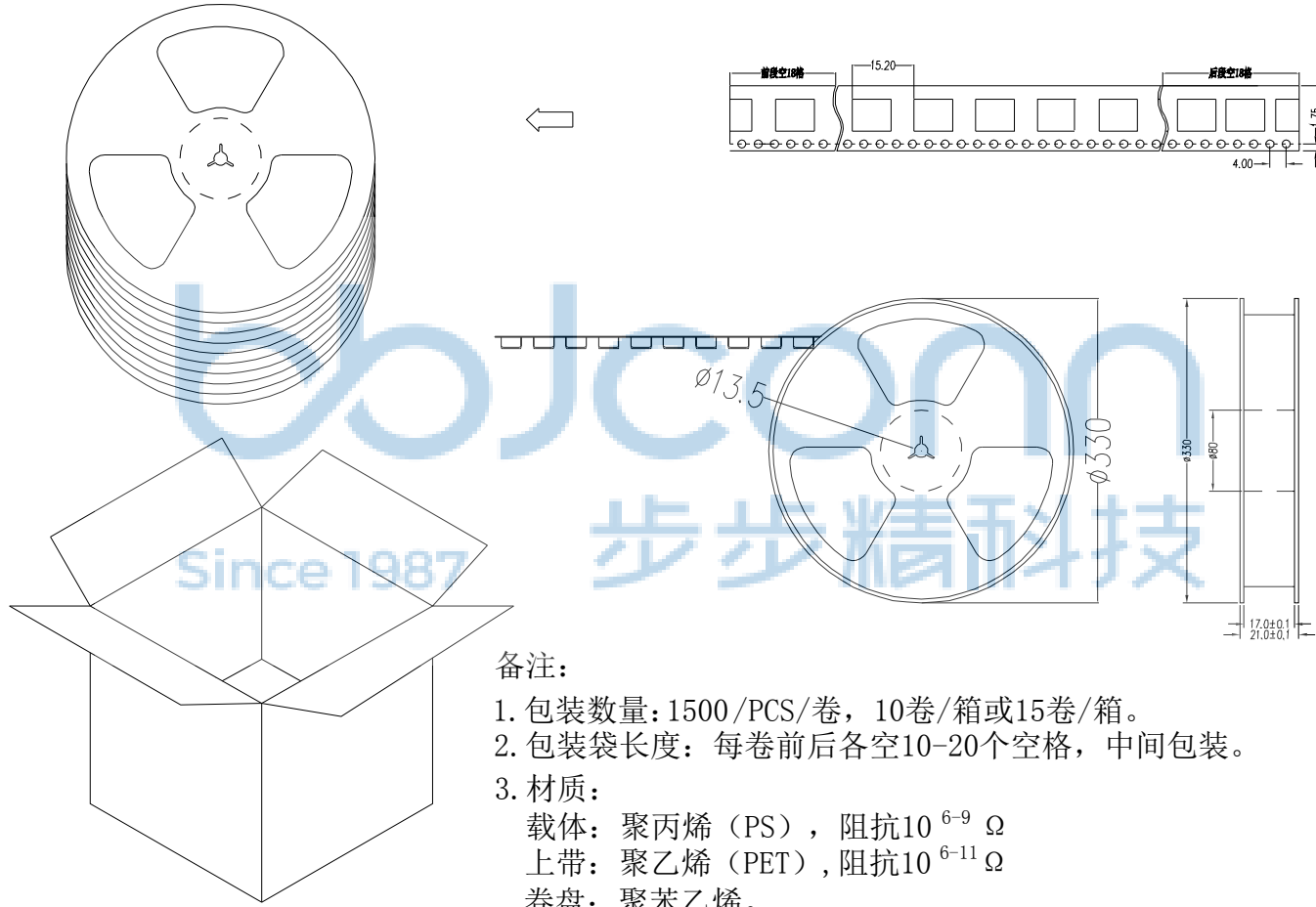


PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
S/W	Switch Pin

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APPD.	JM_Zheng	NAME:	卡座 NANO SIM 6P 掀盖式 贴片 无柱 H=1.40 带检测PIN
CHKD.	LYX	PJ. NO.:	CD.02.02-14-0005
DR.	SGF	SIZE:	A4
PDWG. NO:	0390-1	FINISH:	SEE NOTES
		MAT'L.:	SEE NOTES
		SCALE:	N/A
		REV.:	A0
		UNIT:	mm
		PAGE:	1/2



RECOMMENDED PCB LAYOUT
TOLERANCE ±0.05
SMT SOLDER AREA



备注:

1. 包装数量: 1500/PCS/卷, 10卷/箱或15卷/箱。
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$
卷盘: 聚苯乙烯。

纸箱规格: 345*345*23MM

纸箱规格: 345*345*35MM

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.X: ± 0.38 .XX: ± 0.25 .XXX: ± 0.13		NAME: 卡座 NANO SIM 6P 掀盖式 贴片 无柱 H=1.40 带检测PIN	
APPD.	JM_Zheng	PJ. NO.: CD.02.02-14-0005	
CHKD.	LYX	SIZE: A4 DRW NO.:	
PDWG.NO:	0390-1	FINISH: SEE NOTES	MAT'L.: SEE NOTES
DR.		SCALE: N/A	REV.: A0
		UNIT: mm	PAGE: 2/2